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L2: Entry 1 of 1

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Nov 11, 2004

DERWENT-ACC-NO: 1998-093180² ✓
DERWENT-WEEK: 200475
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TITLE: Wiring tape with adhesive film for multipin semiconductor device e.g. LSI, VLSI, ULSI, BGA - uses film material as thermal stress buffer object whose elasticity in reflow temp range is one or more MPa

INVENTOR: ANJOH, I ; EGUCHI, S ; HATTORI, R ; ISHII, T ; KITANO, M ; KOKAKU, H ; MITA, M ; MIYAZAKI, C ; MORISHIMA, M ; NAGAI, A ; OGINO, M ; OKABE, N ; SEGAWA, M ; TSUBOSAKI, K ; TSUYUNO, N

PATENT-ASSIGNEE:

ASSIGNEE	CODE
HITACHI CABLE LTD	HITD
HITACHI LTD	HITA
HITACHI SEISAKUSHO KK	HITA
ANJOH I	ANJOI
EGUCHI S	EGUCI
HATTORI R	HATTI
ISHII T	ISHII
KITANO M	KITAI
KOKAKU H	KOKAI
MITA M	MITAI
MIYAZAKI C	MIYAI
MORISHIMA M	MORII
NAGAI A	NAGAI
OGINO M	OGINI
OKABE N	OKABI
SEGAWA M	SEGAI
TSUBOSAKI K	TSUBI
TSUYUNO N	TSUYI

PRIORITY-DATA: 1996JP-0136159 (May 30, 1996)

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PATENT-FAMILY:

PUB-NO	PUB-DATE	LANGUAGE	PAGES	MAIN-IPC
<input type="checkbox"/> US 20040224149 A1	November 11, 2004		000	B32B015/04

<input type="checkbox"/> JP 09321084 A	December 12, 1997	012	H01L021/60
<input type="checkbox"/> KR 97077572 A	December 12, 1997	000	H01L023/28
<input type="checkbox"/> TW 345724 A	November 21, 1998	000	H01L023/12
<input type="checkbox"/> US 6114753 A	September 5, 2000	000	H01L023/485
<input type="checkbox"/> JP 3195236 B2	August 6, 2001	013	H01L021/60
<input type="checkbox"/> US 20020160185 A1	October 31, 2002	000	B32B007/12
<input type="checkbox"/> US 6791194 B1	September 14, 2004	000	H01L023/48

APPLICATION-DATA:

PUB-NO	APPL-DATE	APPL-NO	DESCRIPTOR
US20040224149A1	May 16, 1997	1997US-0857674	Div ex
US20040224149A1	January 28, 2000	2000US-0493208	Cont of
US20040224149A1	May 6, 2002	2002US-0138485	Cont of
US20040224149A1	December 1, 2003	2003US-0724092	
US20040224149A1		US 6114753	Div ex
JP 09321084A	May 30, 1996	1996JP-0136159	
KR 97077572A	May 29, 1997	1997KR-0021685	
TW 345724A	May 13, 1997	1997TW-0106369	
US 6114753A	May 16, 1997	1997US-0857674	
JP 3195236B2	May 30, 1996	1996JP-0136159	
JP 3195236B2		JP 9321084	Previous Publ.
US20020160185A1	May 16, 1997	1997US-0857674	Div ex
US20020160185A1	January 28, 2000	2000US-0493208	Cont of
US20020160185A1	May 6, 2002	2002US-0138485	
US20020160185A1		US 6114753	Div ex
US 6791194B1	May 16, 1997	1997US-0857674	Div ex
US 6791194B1	January 28, 2000	2000US-0493210	
US 6791194B1		US 6114753	Div ex

INT-CL (IPC): B32 B 7/12; B32 B 15/04; B32 B 31/00; H01 L 21/60; H01 L 23/12; H01 L 23/28; H01 L 23/48; H01 L 23/485; H01 L 23/495

RELATED-ACC-NO: 2000-132591 ;2000-132593 ;2000-132594 ;2001-630115

ABSTRACTED-PUB-NO: JP 09321084A

BASIC-ABSTRACT:

The wiring tape includes a film material (2.2) which is used as buffer object for thermal stress produced according to the coefficient of thermal expansion of semiconductor device (2.3) and a mounting substrate.

The elasticity of film material is one or more MPas in the reflow temperature range that is 200-250degC.

ADVANTAGE - Raises mass production nature. Excels in flatness.

ABSTRACTED-PUB-NO:

US 6114753A

EQUIVALENT-ABSTRACTS:

The wiring tape includes a film material (2.2) which is used as buffer object for thermal stress produced according to the coefficient of thermal expansion of semiconductor device (2.3) and a mounting substrate.

The elasticity of film material is one or more MPas in the reflow temperature range that is 200-250degC.

ADVANTAGE - Raises mass production nature. Excels in flatness.

CHOSEN-DRAWING: Dwg.2/8

TITLE-TERMS: WIRE TAPE ADHESIVE FILM MULTIPIN SEMICONDUCTOR DEVICE LSI VLSI FILM MATERIAL THERMAL STRESS BUFFER OBJECT ELASTIC REFLOW TEMPERATURE RANGE ONE MORE

ADDL-INDEXING-TERMS:
SEMICONDUCTOR PACKAGE

DERWENT-CLASS: P73 U11

EPI-CODES: U11-D03A1B; U11-E01B;

SECONDARY-ACC-NO:

Non-CPI Secondary Accession Numbers: N1998-074412

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